IPC ASSOCIATION ELECTRONIC	Material Com © Copyright 2005. international and P	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.			nder both	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with low level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Typ http://www.ipc.org/IPC-175x Distribute				Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater				laterials and	ials and Mfg Information				
upplier	r Information														
ompany	name*	Company unique ID			τ	Unique ID Authority				Respo	Response Date*				
onsemi											2025-	2025-06-08			
Contact Name			Title - Contact			F	Phone - Contact*				Emai	Email - Contact*			
Product-F	Env-Stewards		Product Enviro Compliance			1	NA				Prod	Product-Env-Stewards@onsemi.com			
Authorized Representative*			Title - Representative			F	Phone - Representative*				Emai	Email - Representative*			
roduct-F	Env-Stewards	Product Enviro Compliance]	NA				Prod	Product-Env-Stewards@onsemi.com				
	Requester Item Number Mfr Item		m Number Mfr Item Name				Effective Date	Version	M	Manufacturing Site		Weight*	UOM	Unit Type	
		BDW93CTU NPN DARL/10A/1		100V TO-220		2025-06-08 CP8			2030.181	mg	Each				
lanufa	cturing Process Inform		Terminal Base	Alloy	-STD-020 MS	I Dating	Dook Droop	oss Pody T	'amnaratur	Max Time at	Dook Tompo	rotura Numbo	er of Reflow Cyc	plag	
	,		CU Allov NA			L Kaung	0	ess body 1	C	30	T .	onds 3	of Kellow Cyc	cies	
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RoHS Material Composition Declaration			Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (100 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).										
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its keloartion shall encompass all such completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, itssuppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies of Supplier's Standard Terms and/Conditions of Sale applicable to such part shall apply.										
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted substance	s per the definition above except for selected exemp	tions Supplier Acceptance	* Accepted						
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).										
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.										
Supplier Digital Signature Ra	astislav Drska	-En								

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	2.81	mg	Supplier	Silicon (Si)	7440-21-3		2.81	mg
Die Attach Solder	1.111		Supplier	Silver (Ag)	7440-22-4		0.0278	mg
			A	Lead (Pb)	7439-92-1	7a	1.0277	mg
			Supplier	Tin (Sn)	7440-31-5		0.0555	mg
Lead Frame	1492.12		В	Nickel (Ni)	7440-02-0		0.1492	mg
			Supplier	Iron (Fe)	7439-89-6		1.4921	mg
			Supplier	Copper (Cu)	7440-50-8		1490.031	mg
			Supplier	Phosphorus (P)	7723-14-0		0.4476	mg
Mold Compound-Black	518.4		В	Brominated Bisphenol A Diglycidyl Ether	40039-93-8		10.368	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		44.064	mg
			В	Antimony Trioxide (Sb2O3)	1309-64-4		7.776	mg
			Supplier	Carbon Black (C)	1333-86-4		2.592	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		414.72	mg
			Supplier	Silica (SiO2)	14464-46-1		5.184	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		33.696	mg
Plating	13.3	mg	Supplier	Tin (Sn)	7440-31-5		13.3	mg
Wire Bond - Al	2.44	mg	Supplier	Aluminum (Al)	7429-90-5		2.44	mg